

Appn No. 10/040,456
Amdt. Dated December 12, 2003
Reply to Office action of October 21, 2003

2

Amendments to the Specification:

The Paragraph beginning at Page 4, lines 26 to 32, to be amended as follows:

--An array of caps 48 is formed using conventional injection molding methods and steel mold tools 50 & 52. The caps are supported on a sprule 54 at the same nominal spacing as the groups 42. Using this method will almost invariably lead to misalignment with resulting destruction of MEMS devices, as shown in figure 20 7. In figure 20 7 the cap 48a has been aligned correctly with its group of MEMS devices 42a. However the spacing between the caps is greater than the spacing of the groups so that cap 48b is not aligned correctly, but does not destroy any of the MEMS devices of its respective group 42b.--

The Paragraph beginning at Page 6, lines 3 to 5, to be amended as follows:

The two surfaces have been etched so that the groove 112 for the perimeter of the cap is all in the lower wafer 104 and the recess 104 106 for the central portion is all in the upper wafer 102.

The Paragraph beginning at Page 9, lines 10 to 13, to be amended as follows:

Whilst still attached to the upper mold, the sheet 134 is then subject to an etch, preferably an oxygen plasma etch, from below, to remove the thin layer 140 of material, as shown in figure 17. The etch has little effect on the rest of the material due to the significant greater ~~in~~ thickness of the rest of the material. The etched assembly is shown in figure 18.